

MC908AP48CFBE Information

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General Information

Parameter	Value
Part Number	MC908AP48CFBE
Description	MCU,48K FLASH,10 BIT ADC
Product Line	G9G8AP64
PTI	MDNS
Material Type	Tested Packaged Device
Life Cycle Description (code)	NOT RECOMMENDED(DECLINING)
Status	Not Recommended for New Design
Application/Qualification Tier	10-YEARS APPLICATION LIFE

Package Information

Parameter	Value
Package Type and Termination Count	QFP 44
Package Description and Mechanical Drawing	QFP44 10*10*2.0P0.8
Device Weight(g)	.49860
Package Material	Plastic
Mounting Style	Surface Mount
Package Length (nominal)(mm)	10.000
Package Width (nominal)(mm)	10.000
Package Thickness (nominal)(mm)	2.450
Tape & Reel	No

Environmental and Compliance Information

Parameter	Value
Pb-Free	
RoHS Compliant	
Halogen Free	Yes
Material Composition Declaration (MCD)	Download MCD Report  Download MCD Report 
RoHS Certificate of Analysis (CoA)	Download RoHS CoA Report
2nd Level Interconnect	e3
Moisture Sensitivity Level (MSL)	3
Floor Life	168 HOURS
Peak Package Body Temperature (PPT)(°C)	260
Maximum Time at Peak Temperature (s)	40
Number of Reflow Cycles	3
REACH SVHC	Freescale REACH Statement
UL94 (plastics flammability test)	V0: Burning stops within 10 seconds on a vertical specimen; no drips allowed

Manufacturing Information

Parameter	Value
Micron Size(?m)	.25

Ordering Information

Parameter	Value
Minimum Package Quantity (MPQ)	480
MPQ Container	BRICK
Exempt from Minimum Delivery Value	No
Preferred Order Quantity (POQ)	480
POQ Container	BOX
Leadtime (weeks)	8
Export Control Classification Number (US)	EAR99
Harmonized Tariff (US) Disclaimer	8542.31.0000
CCATS Document	-
ENC Status	-
Other Trade Compliance Documents	-
Budgetary Price excluding tax(US\$) Change Currency	-
Device Sample Availability	16 Nov 2005
Device Production Availability	16 Nov 2005
Order	

Product/Process Change Notice (PCN)

Number	Type	Title	Issue Date	Effectivity Date
15275	Product Change Notice	0.25UM Copper Wire Qualification	16 Aug 2012	26 Dec 2012
14263	Product Change Notice	20um Au wire qualification for SOIC28/LQFP/QFP packages in FSL-TJN-FM Assembly Site	04 Aug 2010	02 Nov2010
14160	Product Bulletin	MC68HC908AP64 Room Test Elimination	26 May 2010	27 May2010
13804	Product Bulletin	9S08GT16A/9S08GT60A/9S08GT60/9RS08KA8/9S08JR12/9S08RX32/HC908AP64 Final test site transfer from FSL-TJN-FM to KES-CHINA	31 Aug 2009	02 Sep 2009
13132A	Update Notification	MSG8 908AP64 PROBE SITE TRANSFER CLARIFICATION	14 May 2008	15 May2008
13132	Product Bulletin	MSG8 908AP64 PROBE SITE TRANSFER	05 Feb 2008	06 Feb 2008
12504	Product Bulletin	TSPG MCD8 908AP64 TEST TRANSFER	06 Feb 2007	07 Feb 2007
12458	Product Bulletin	TSPG MCD8 HC908AP64 TEST SITE EXPANSION	15 Dec 2006	23 Dec 2006
12219	Product Bulletin	908AP64 0M25D HT SINGLE TEST FLOW	21 Jul 2006	22 Jul 2006
12120	Product Change Notice	908AP64 MASKSET 0M25D QUALIFICATION	08 Jun 2006	15 May2006
11623	Product Change Notice	908AP64 EPP PACKAGES QUALIFCATION	27 Dec 2005	27 Mar 2006
11462	Product Bulletin	TSPG MCD ROHS COMPLIANT DEVICE MIGRATION	14 Oct 2005	15 Oct 2005
11431	Product Bulletin	TSPG MCD ROHS COMPLIANT DEVICE MIGRATION	04 Oct 2005	05 Oct 2005

Operating Characteristics

Parameter	Value
Sample Exception Availability	N

[Reliability Data Lookup](#)